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DATA SHEET

PART NO. : LC19DCAIR1CT-XG

REV : A / 0

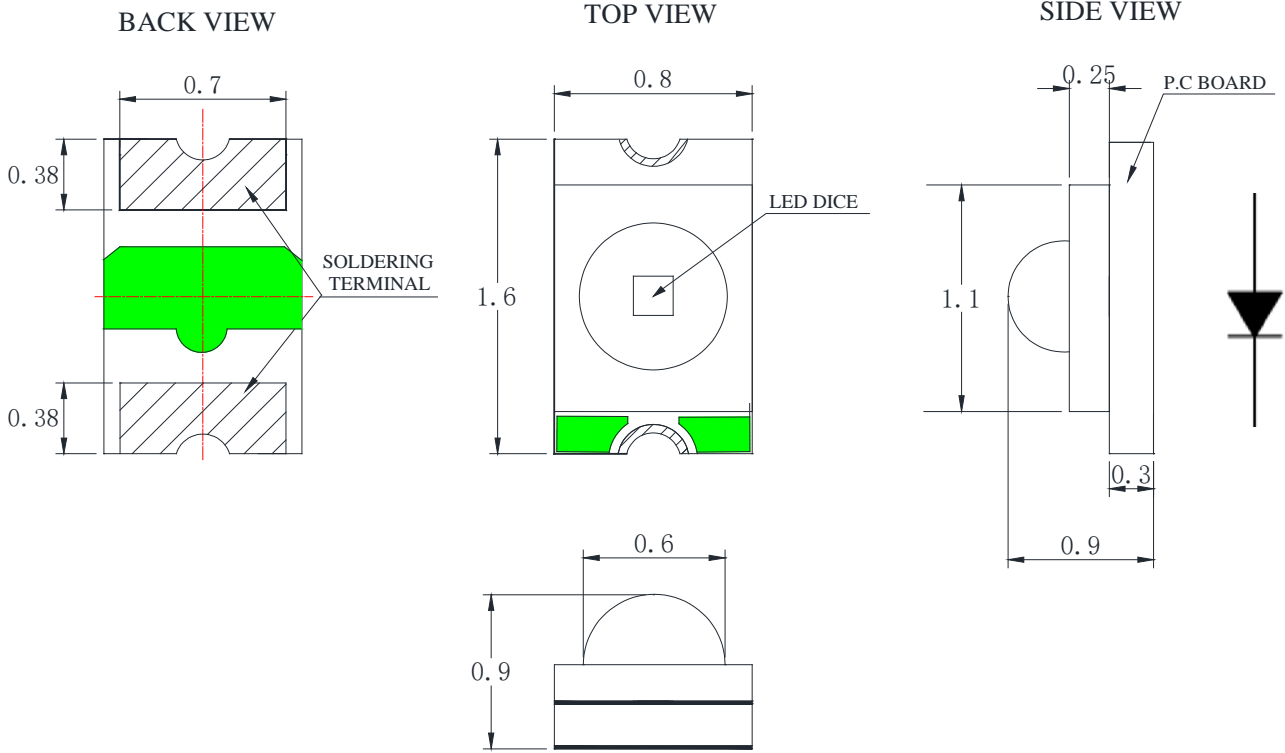
CUSTOMER'S APPROVAL : _____ DCC : _____

DRAWING NO. : DS-52-22-048

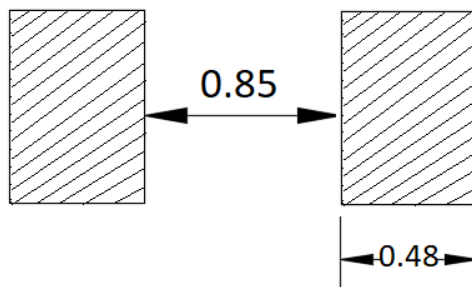
DATE : 2022-06-27

Page : 1

PACKAGE DIMENSIONS



Recommended pad size



NOTES :

- 1.All dimensions are in millimeters
- 2.Tolerances are ± 0.2 mm unless otherwise noted
- 3.The Specifications in the datasheet are subject to change without notice.



SURFACE MOUNT DEVICE LED

LC19DCAIR1CT-XG

REV:A / 0

FEATURES

- Dimension (L / w / h): 1.6 x 0.8 x 0.9 mm
- Color: Infrared light
- Colloid: transparent spherical colloid
- EIA standard packaging
- Environmental protection products meet ROHS requirements
- Suitable for automatic placement machine
- Suitable for infrared reflow soldering process

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

Symbol	Parameter	Rating	Unit
PD	Power consumption	60	mW
If	Forward Current	30	mA
Ifp	Peak Forward Current (1/10 duty cycle 0.1ms)	80	mA
VR	Reverse Voltage	5	V
ESD	Electrostatic discharge (HBM)	1000	V
Topr	Operating Temperature Range	-30°C ~ + 85°C	°C
Tstg	Storage Temperature Range	-40°C ~ + 90°C	°C
Tsol	Reflow soldering : 255°C ,10s, Hand soldering : 300°C ,3s		

Note: Pulse width ≤ 0.1 ms,Duty $\leq 1/10$

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiation intensity	IE	1	-	7	mW/sr	IF=20mA
Viewing Angle	2 θ 1/2	-	60	-	deg	IF=20mA
Dominant Wavelength	WD	-	940	-	nm	IF=20mA
Forward Voltage	VF	1.1	-	1.4	V	IF=20mA
Reverse Current	IR	-	-	3	μ A	VR=5V



SURFACE MOUNT DEVICE LED

LC19DCAIR1CT-XG

REV:A / 0

Bin Code List

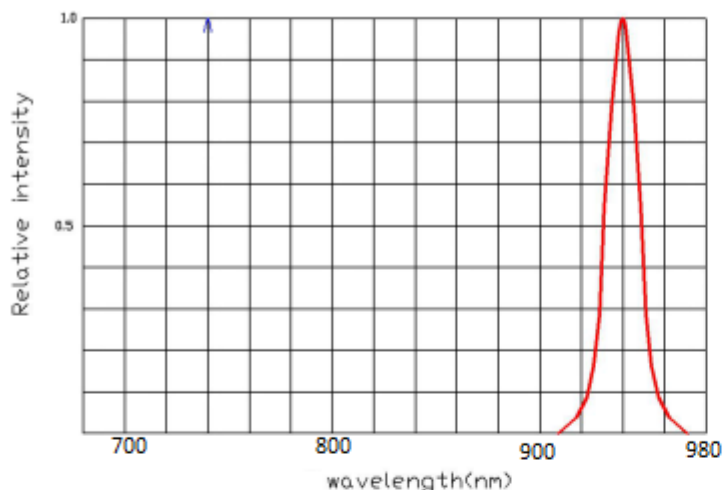
Parameter	Symbol	Min.	Max.	Unit	Test Condition
Radiation intensity	IE	1	3	mW/sr	IF =20mA
		3	5		
		5	7		

Label marking error:

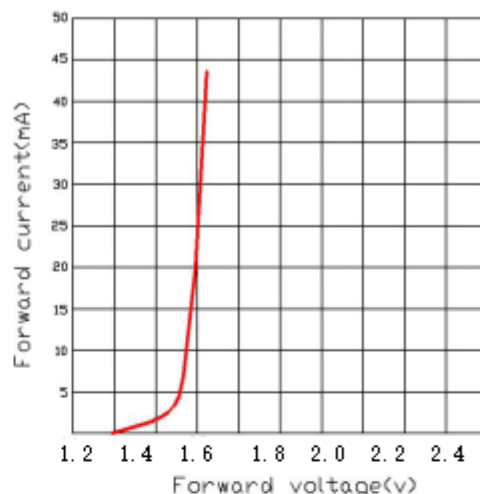
1. Tolerance of measurement of Radiation intensity is $\pm 20\%$.
2. Tolerance of measurement of dominant wavelength is $\pm 1\text{nm}$.
3. Tolerance of measurement of Vf is $\pm 0.1\text{ V}$.

Typical Electro-Optical Characteristics Curves

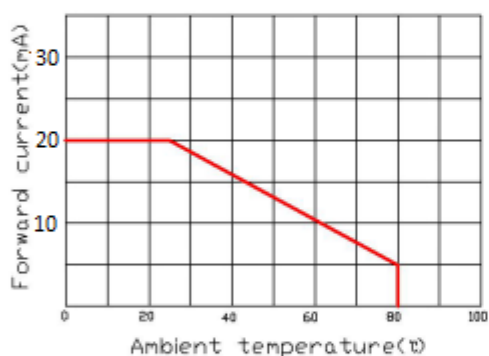
Relative intensity VS wavelength



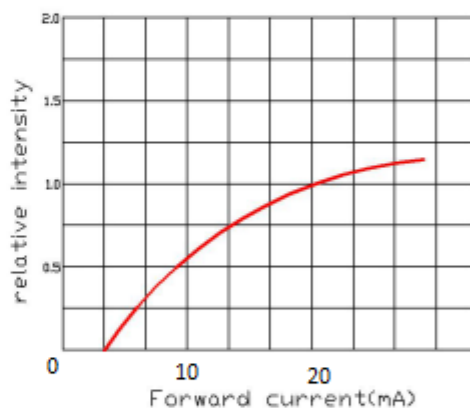
Voltage current relationship



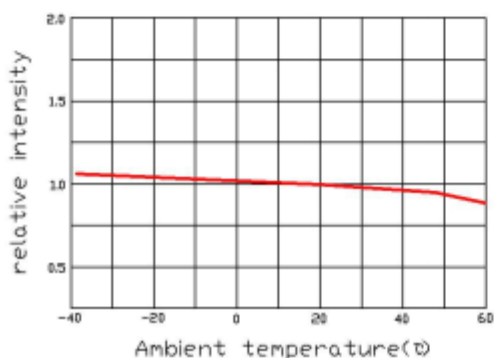
Current and ambient temperature



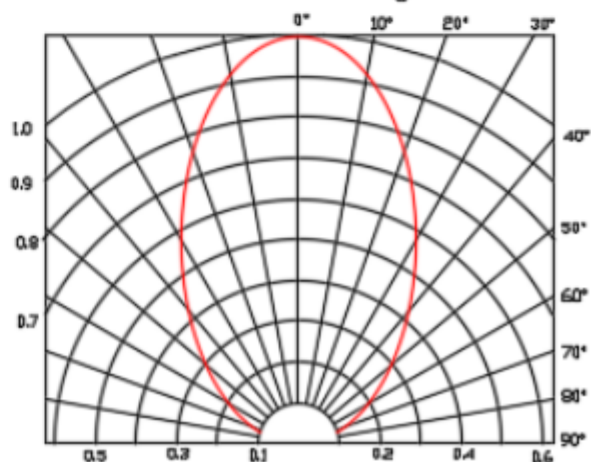
Relative light intensity vs current



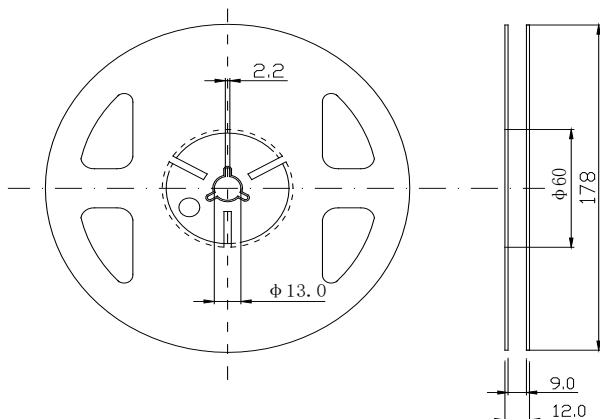
Relative light intensity vs ambient temperature



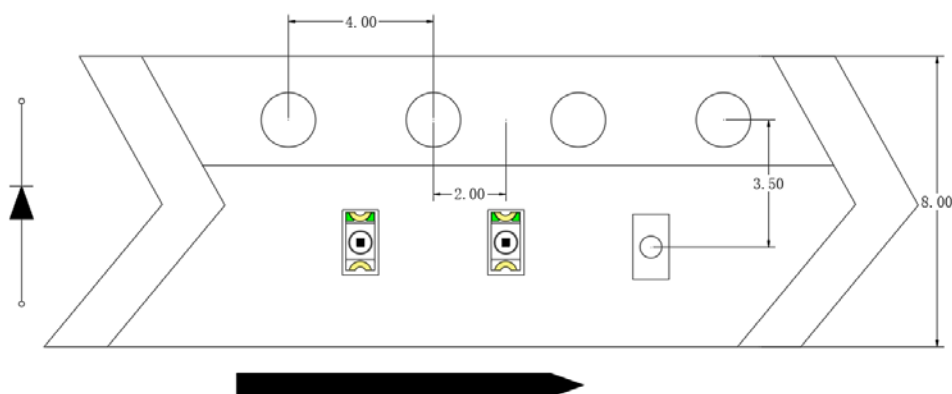
Radiation angle



Reel Dimensions



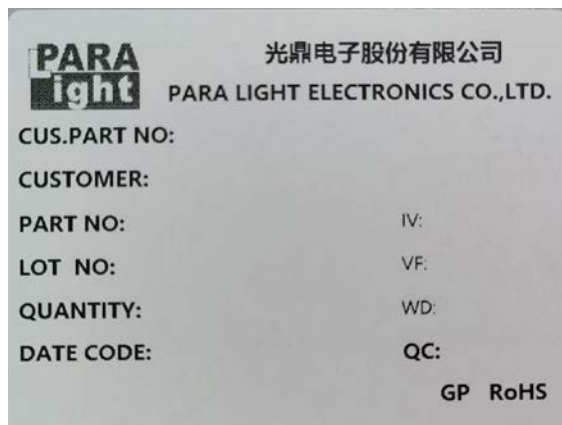
Package Dimensions Of Tape And Reel



Notes:

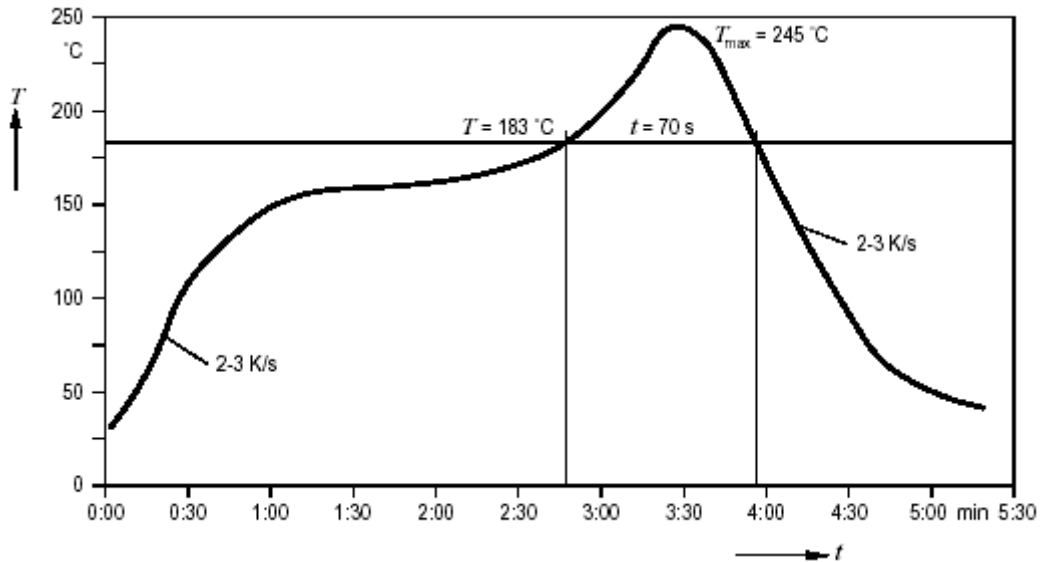
1. Taping Quantity : 4000pcs
2. The tolerances unless mentioned is $\pm 0.15\text{mm}$

Label Explanation

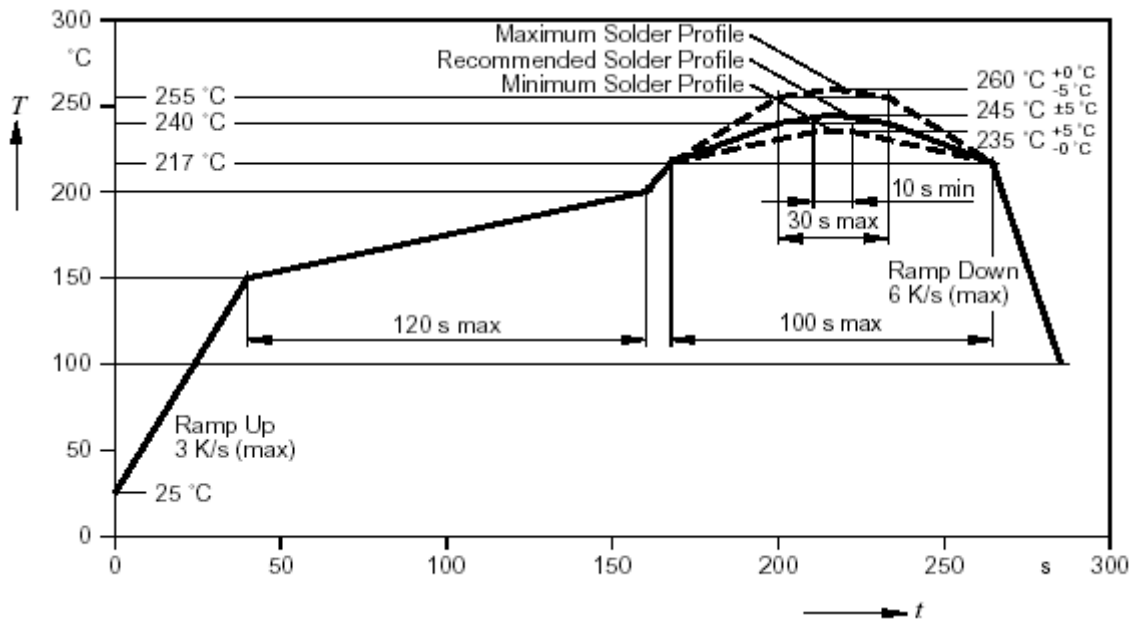


ITEM CODE:PARA LIGHT
 PART NO: LC19DCAIR1CT-XG
 LOT NO: Batch number

Suggest Sn/Pb IR Reflow Soldering Profile Condition:



Suggest Pb-Free IR Reflow Soldering Profile Condition:



Cleaning

- * If cleaning is required , use the following solutions for less than 1 minute and less than 40°C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- * Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

CAUTIONS

1.Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application).Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage :

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours.

3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150°C, 120sec. MAX., Peak temperature : 240°C Max. Soldering time : 10 sec Max.

Soldering Iron : (Not recommended)

Temperature 300°C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering :

Pre-heat 100°C Max, Pre-heat time 60 sec. Max, Solder wave 260°C Max, Soldering time 5 sec. Max. preformed consecutively cooling process is required between 1st and 2nd soldering processes.

4. Lead-Free Soldering

For Reflow Soldering :

- 1、 Pre-Heat Temp:150-180°C,120sec.Max.
- 2、 Soldering Temp:Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、 Peak Temperature:260°C , 5sec.
- 4、 Reflow Repetition:2 Times Max.
- 5、 Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

For Soldering Iron (Not Recommended) :

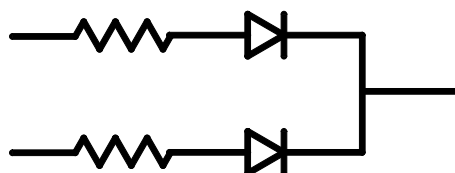
- 1、 Iron Tip Temp:350°C Max.
- 2、 Soldering Iron:30w Max.
- 3、 Soldering Time:3 Sec. Max. One Time.

For Dip Soldering :

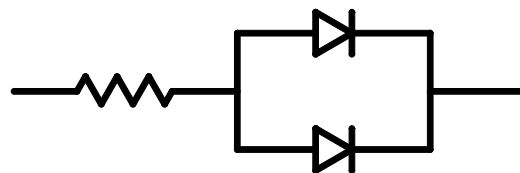
- 1、 Pre-Heat Temp:150°C Max. 120 Sec. Max.
- 2、 Bath Temp:265°C Max.
- 3、 Dip Time:5 Sec. Max.

5. Drive Method

Circuit model A



Circuit model B



(A)Recommended circuit.

(B)The difference of brightness between LED`s could be found due to the Vf-I_f characteristics of LED.